#3/Pal-a w/Sub-Spac



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moon et al.

Serial No.: 09/874,631

Filed: June 5, 2001

For: FLEXIBLE BALL GRID ARRAY CHIP SCALE PACKAGES AND METHODS OF

FABRICATION

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 4368US(99-0959)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20031

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Darlene Holt
Typed/printed name of person whose signature is contained above

PRELIMINARY AMENDMENT

Box Non-Fee Amendment Commissioner for Patents Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.